



**INNOLAS**  
solutions



MEMBER OF  
**PHOTONICS  
SYSTEMS  
GROUP**

INNOVATION FOR THE  
NEXT GENERATION



# **DIVIDOS** Series

**LASER DEPANELING SYSTEMS**  
FOR THE ELECTRONIC INDUSTRY

## **BENEFITS**

- ◆ No tooling costs and better TCO
- ◆ Full cut with 30% more panels on board
- ◆ High edge quality and less residuals on board
- ◆ No carbonization
- ◆ Cutting of any shape compared to mechanical cut
- ◆ Cost effective design
- ◆ Simple and easy to maintain
- ◆ Dedicated solution for PCB depaneling
- ◆ Industry 4.0 ready

## **OPTIONS**

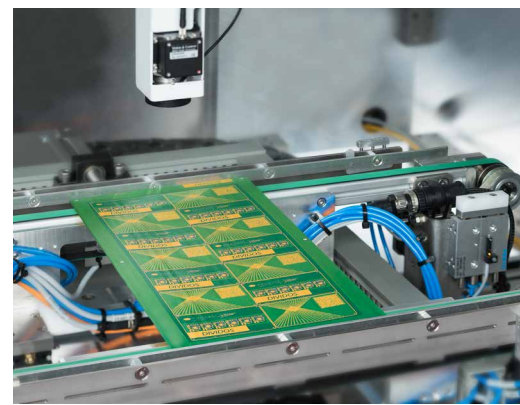
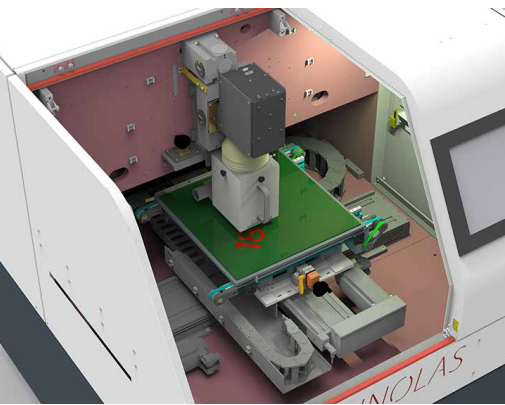
- ◆ 2nd process head (galvo scanner)
- ◆ Postprocessor for CAD file transfer
- ◆ Exhaust system
- ◆ MES Interface
- ◆ Different carrier options

## **TECHNOLOGY**

- ◆ High speed Galvo Scanner
- ◆ Automatic calibration routines
- ◆ InnoLas  $\mu$ Vision
- ◆ Windows 10 IoT
- ◆ Touch display

## **AUTOMATION**

- ◆ Fully automated system
- ◆ Stand alone system
- ◆ S/ME/MA compliant



## **APPLICATIONS**

Laser Depaneling/ Laser Routing

## **ACCURACY**

< +/-50  $\mu$ m

## **SUBSTRATE**

Dimension up to 18" x 18" (457 x 457 mm)

## **LASER**

ns UV, ns green, ps IR

## **DIMENSIONS**

1440 x 1521 mm x 1596 mm Weight: 1100 kg;  
( 57 x 60 x 63 Inches ) (Weight 2420 lbs)

